

(19) World Intellectual Property
Organization
International Bureau



(43) International Publication Date
19 August 2004 (19.08.2004)

PCT

(10) International Publication Number
WO 2004/070778 A2

(51) International Patent Classification⁷: **H01L**

(21) International Application Number:
PCT/US2004/002080

(22) International Filing Date: 27 January 2004 (27.01.2004)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:

60/442,952	27 January 2003 (27.01.2003)	US
60/461,147	8 April 2003 (08.04.2003)	US
60/462,015	11 April 2003 (11.04.2003)	US
60/464,280	21 April 2003 (21.04.2003)	US
60/466,587	30 April 2003 (30.04.2003)	US
60/468,239	5 May 2003 (05.05.2003)	US
60/468,561	6 May 2003 (06.05.2003)	US
60/477,489	10 June 2003 (10.06.2003)	US

(81) Designated States (*unless otherwise indicated, for every kind of national protection available*): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

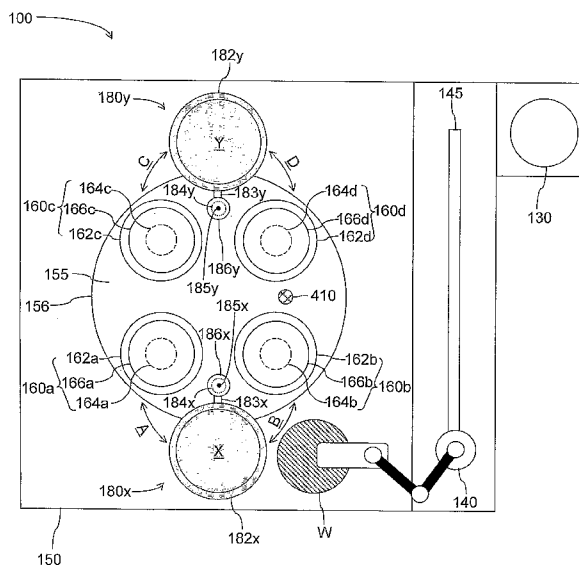
(84) Designated States (*unless otherwise indicated, for every kind of regional protection available*): ARIPO (BW, GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:

— without international search report and to be republished upon receipt of that report

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

(54) Title: APPARATUS AND METHOD FOR POLISHING SEMICONDUCTOR WAFERS USING ONE OR MORE PIVOTABLE LOAD-AND-UNLOAD CUPS



(57) Abstract: An apparatus and method for polishing objects, such as semiconductor wafers, utilizes one or more pivotable load-and-unload cups to transfer the objects to and/or from one or more object carriers to polish the objects. Each pivotable load-and-unload cup may be configured to transfer the objects to and/or from a single object carrier. Alternatively, each pivotable load-and-unload cup may be configured to transfer the objects to and/or from two object carriers. The pivotable load-and-unload cups may be configured to be pivoted about one or more pivoting points over at least one polishing surface, such as a polishing pad surface.

WO 2004/070778 A2